



Attorney Docket No.: PATENT
COOL-00800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:) Group Art Unit: 3753
Girish Upadhyia et al.) Examiner:
Serial No.: 10/698,180) <u>TRANSMITTAL LETTER</u>
Filed: October 30, 2003) 162 N. Wolfe Road
For: OPTIMAL SPREADER SYSTEM, DEVICE AND METHOD FOR FLUID COOLED MICRO-SCALED HEAT EXCHANGE) Sunnyvale, CA 94086 (408) 530-9700
) Customer No.: 28960

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

Enclosed please find an Information Disclosure Statement and Form PTO-1449, including copies of the references contained thereon, for filing in the U.S. Patent and Trademark Office.

You will also find enclosed the associated Transmittals, Electronic Information Disclosure Statements, and United States Patent and Trademark Office Acknowledgment Receipts for the electronically filed Information Disclosure Statement (EFS ID #57478); (EFS ID #57479); (EFS ID #57481); and (EFS ID #57483) filed on March 19, 2004.

The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 3/19/04

By: Thomas B. Haverstock
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CERTIFICATE OF MAILING (37 CFR § 1.8(a))

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to the: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450

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Date: 3-19-04 By: [Signature]



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For: OPTIMAL SPREADER SYSTEM,)	<u>STATEMENT</u>
DEVICE AND METHOD FOR)	
FLUID COOLED MICRO-SCALED)	162 N. Wolfe Road
HEAT EXCHANGE)	Sunnyvale, CA 94086
)	(408) 530-9700

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #57478); (EFS ID #57479); (EFS ID #57481); and (EFS ID #57483). Applicants have become aware of the following printed publication which may be material to the examination of this application:

- Chinese Publication No. CN 97212126.9;
- Japanese Patent Abstract JP 2000-277540;
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Respectfully submitted,
HAVERSTOCK & OWENS LLP

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Examiner:		/Ljiljana Ciric/ (05/11/2009)				Date Considered: 05/11/2009	
EXAMINER:		Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.					

FORM PTO-1449 (Modified)		U.S. Department of Commerce Patent and Trademark Office		Attorney Docket No.: COOL-00800		Serial No.: 10/698,180	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)				Applicants: Girish Upadhyaya et al.			
				Filing Date: October 30, 2003		Group Art Unit: 3753	
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Applicants: Girish Upadhyaya et al.

(37 CFR § 1.98(b))

Filing Date: October 30, 2003

Group Art Unit: 3753

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Examiner: /Ljiljana Ciric/ (05/11/2009)

Date Considered: 05/11/2009

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT
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Applicants: Girish Upadhyaya et al.

(37 CFR § 1.98(b))

Filing Date: October 30, 2003

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	GM	D. B. Tuckerman et al., High-Performance Heat Sinking for VLSI, 1981, IEEE Electron Device Letters, Vol. EDL-2, No. 5, pages 126-129.
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Electronic Version 1.1
Stylesheet Version v1.1.1

Title of Invention	OPTIMAL SPREADER SYSTEM, DEVICE AND METHOD FOR FLUID COOLED MICRO-SCALED HEAT EXCHANGE										
Submission Type:	Information Disclosure Statement										
Application Number:	10/698180	*10/698180*									
EFS ID:	S7478										
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First Named Applicant:	Girish Upadhya										
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Page 2 of 2

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Transmittal

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Page 2 of 2

TRANSMITTAL Electronic Version v1.1 Stylesheet Version v1.1.0			
Title of Invention OPTIMAL SPREADER SYSTEM, DEVICE AND METHOD FOR FLUID COOLED MICRO-SCALED HEAT EXCHANGE	Application Number: 10/698180 Date: 2003-10-30 First Named Applicant: Clirich Upadhyaya Confirmation Number: 9903 Attorney Docket Number:		
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Submitted by: Thomas B. Haverstock Registered Number: 32571	<table border="1"> <tr> <td>Elec. Sign. /tbh/</td> <td>Sign. Capacity Attorney</td> </tr> </table>	Elec. Sign. /tbh/	Sign. Capacity Attorney
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
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Title of Invention	OPTIMAL SPREADER SYSTEM, DEVICE AND METHOD FOR FLUID COOLED MICRO-SCALED HEAT EXCHANGE						
Application Number:	10/698180	*10/698180*					
Confirmation Number:	9903						
First Named Applicant:	Girish Upadhye						
Attorney Docket Number:							
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
Int.	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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45	5336062	1994-08-09	Richter
46	5380956	1995-01-10	Loe et al.
47	5383340	1995-01-24	Larson et al.
48	5427174	1995-08-27	Lomelino, Sr. et al.
49	5436793	1995-07-25	Samwo et al.
50	5459099	1995-10-17	Hsu

Signature

Examiner Name	Date